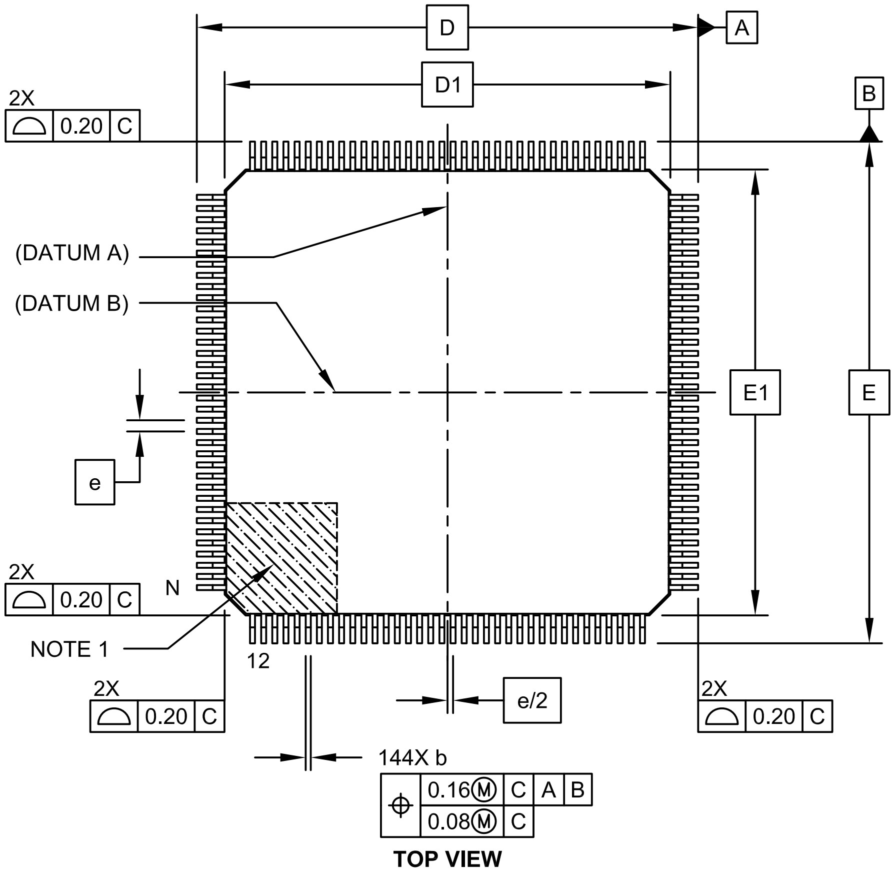
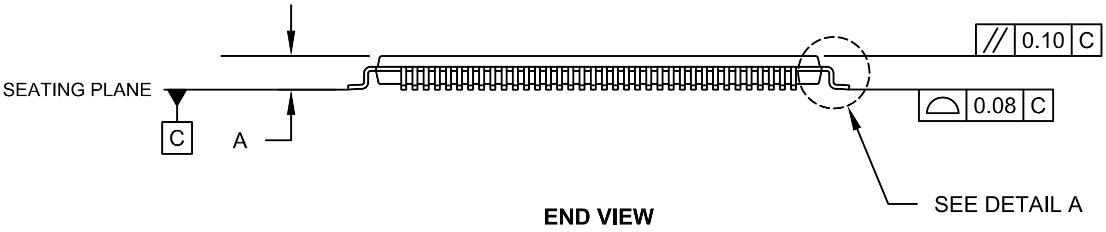
# 144-Lead Plastic Thin Quad Flatpack (PH)-16x16x1mm Body, 2.00 mm Footprint [TQFP]

| | |
|---|---|
| **Note:** | For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging |





Microchip Technology Drawing C04-155B Sheet 1 of 2

# 144-Lead Plastic Thin Quad Flatpack (PH)-16x16x1mm Body, 2.00 mm Footprint [TQFP]

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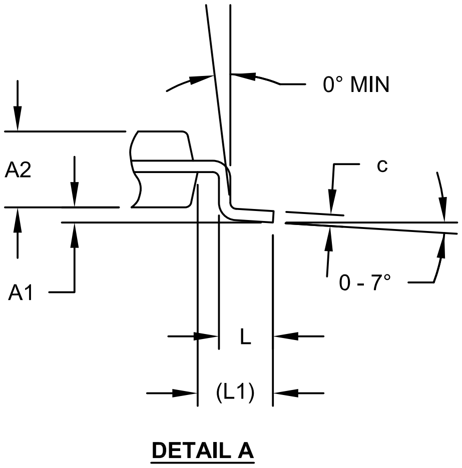

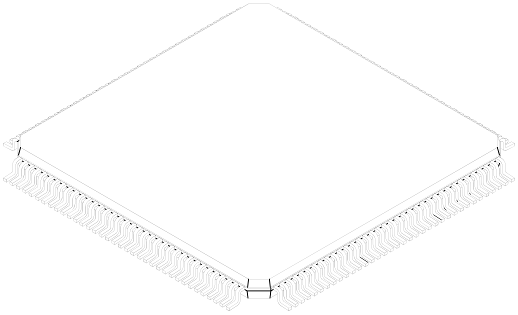

| Units | | MILLIMETERS | | |
|---|---|---|---|---|
| Dimension Limits | | MIN | NOM | MAX |
| Number of Pins | N | | 144 | |
| Lead Pitch | e | | 0.40 BSC | |
| Overall Height | A | - | - | 1.20 |
| Molded PackageThickness | A2 | 0.95 | 1.00 | 1.05 |
| Standoff | A1 | 0.05 | - | 0.15 |
| Foot Length | L | 0.45 | 0.60 | 0.75 |
| Footprint | L1 | | 1.00 REF | |
| Overall Width | D | | 18.00 BSC | |
| Overall Length | E | | 18.00 BSC | |
| Molded Body Width | D1 | | 16.00 BSC | |
| Molded Body Length | E1 | | 16.00 BSC | |
| Lead Thickness | c | 0.09 | - | 0.20 |
| Lead Width | b | 0.13 | - | 0.23 |

**Notes:**

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated.
3. Dimensioning and tolerancing per ASME Y14.5M.
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.
   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-155B Sheet 2 of 2

## 144-Lead Plastic Thin Quad Flat Pack (PH) - 16x16 mm Body, 2.00 mm Footprint [TQFP]

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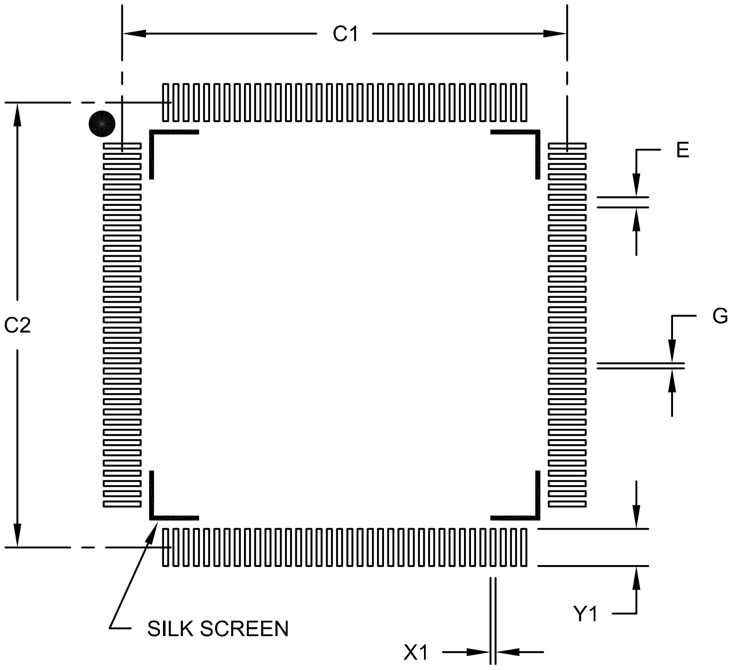

RECOMMENDED LAND PATTERN

| Units | | MILLIMETERS | | |
|---|---|---|---|---|
| Dimension Limits | | MIN | NOM | MAX |
| Contact Pitch | E | 0.40 BSC | | |
| Contact Pad Spacing | C1 | | 17.40 | |
| Contact Pad Spacing | C2 | | 17.40 | |
| Contact Pad Width (X144) | X1 | | | 0.20 |
| Contact Pad Length (X144) | Y1 | | | 1.45 |
| Distance Between Pads | G | 0.20 | | |

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2155B